SODR1A THRU SODR1M

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1.0Amp Fast Recovery Surface Mounted Rectifiers

General description

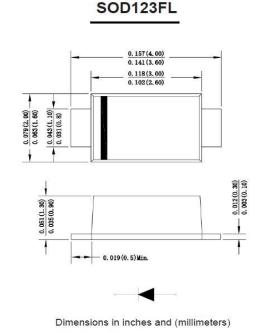
1.0Amp Fast Recovery Surface Mounted Rectifiers

FEATURES

- For surface mounted applications
- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Idea for printed circuit board
- Glass passivated Junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed
- 250 C/10 seconds at terminals

MECHANICAL DATA

- Case: Molded plastic body
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity: Polarity symbol marking on body
- Mounting Position: Any
- Weight: 0.0007 ounce, 0.02 grams



Absolute Maximum Ratings(Ta=25°C unless otherwise specified)

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	SYMBOLS	SOD R1A	SOD R1B	SOD R1D	SOD R1G	SOD R1J	SOD R1J	SOD R1M	UNITS
Maximum repetitive peak reverse voltage	Vrrm	50	100	200	400	600	800	1000	V
Maximum RMS voltage	Vrms	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	Vdc	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at T∟=100°C	l(AV)	1.0							А
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	IFSM	35							A
Maximum instantaneous forward voltage at 1.0A	Vf	1.3							V
Maximum DC reverse current T ឝ=25°C at rated DC blocking voltage Tឝ=125°C	lr	5.0 500							uA
Maxinum reverse recovery time(Note 1)	Trr	150 250 500				ns			
Typical junction capacitance (Note2)	CJ	9.0							pF
Typical thermal resistance	Rqja	85.0							"C/W
Operating junction and storage temperature range	Tj,Tstg	-55 to +150							J.

NOTES: 1. Reverse Recovery Test Conditions: IF=0.5A, IR=1.0A, Irr=0.25A

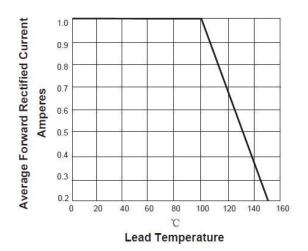
2. Measured at 1 MHz and applied Vr = 4.0 volts.

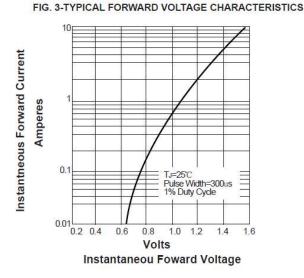




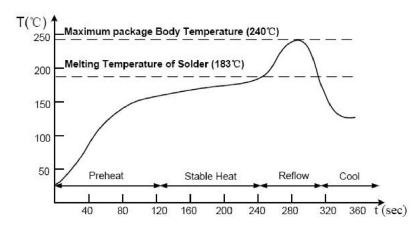
Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT





Suggested Soldering Temperature Profile



Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PERLEG

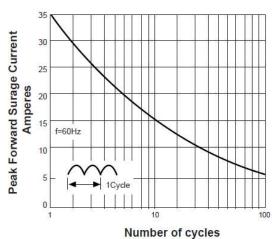
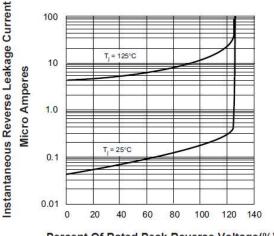


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



Percent Of Rated Peak Reverse Voltage(%)



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